

SEMICONDUCTOR PACKAGE AND PRODUCTION METHOD

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ABSTRACT OF THE DISCLOSURE

10 A plurality of semiconductor packages is collectively fabricated on a wafer in a batch process and the wafer is then diced to obtain discrete semiconductor packages. The semiconductor package is a stacked body formed by bonding two or more semiconductor devices. Each semiconductor device comprises a substrate and a device pattern formed on a surface of the substrate. The  
15 semiconductor devices are stacked in such a fashion that a device pattern surface of the lower semiconductor device faces a non-device pattern surface of the semiconductor device stacked on the same.